



PATENT

JFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/772,311 Group Art Unit: 1732
Filing Date: February 6, 2004 Examiner: Lee, Edmund H.
Applicant: Sang-Hyeop LEE et al.
Title: MOLDING METHOD AND MOLD FOR
ENCAPSULATING BOTH SIDES OF PCB MODULE
WITH WAFER LEVEL PACKAGE MOUNTED PCB
Attorney Docket: 2557-000220/US

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July 24, 2009

AMENDMENT UNDER § 1.312

Sir:

In response to the Notice of Allowance mailed July 2, 2009, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Claims begin on page 2 of this Amendment.

Remarks begin on page 6 of this Amendment.

| | Claims remaining after Amendment | | Highest number previously paid for | | Present extra |
|--------------------|-------------------------------------|---|---------------------------------------|---|---------------|
| Total | 9 | - | 20 | = | 0 |
| Independent | 2 | - | 3 | = | 0 |